

# semiconductor packaging news

EV Group Hybrid Bonding and NIL Solutions Highlighted at SEMICON Taiwan – August 31, 2023

## semiconductor packaging news

We search for industry news, so you don't need to.

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August 31, 2023

### [US Chip War Not Enough to Deter China's Military Ambitions](#)

Despite the intensifying US-China chip war, China remains undeterred in its military ambitions, according to Asia Times. The ongoing technological standoff has seen the US restrict chip exports to China, aiming to curb its military modernization. However, experts argue that ...

Asia Times



[SUMMARY](#)

### [Keys to Reliable Tin Mitigation](#)

A more reliable method to mitigate tin whiskers is the robotic hot solder dip processing of components before assembly. This white paper identifies the key process considerations. [Read more.](#)



Circuit Technology Center

### [Efficient Manufacture of IR Sensors](#)

The market for IR sensing devices has been growing steadily but the challenge is how to manufacture them efficiently to achieve ROI. [Read more.](#)



Palomar Technologies, Inc.

### [Challenges In Ramping New Manufacturing Processes](#)

Ramping up novel manufacturing processes within the semiconductor industry presents formidable challenges. As demand surges for ...

Semiconductor Engineering

[SUMMARY](#)

### [Improving SiC Power Devices with Laser Ohmic Contact Formation](#)

Learn about the impact of laser-based OFC on the electrical characteristics of SiC-Ni interfaces and its effect on surface structures, including with thin wafers.

Technical Paper

[DOWNLOAD](#)

### [ASML secures approval to invest over NT\\$10 billion in Taiwan](#)

Taiwan's semiconductor industry receives a major boost as TSMC, the world's leading chipmaker, announces plans to ...

Focus Taiwan

[SUMMARY](#)

### Technical Papers

- [3D Sensing Solutions](#)
- [Critical Cleaning Requirements to Overcome Advanced Packaging and Deflusing Challenges](#)
- [Reliably Reinforce BGAs While Minimizing Stress on Solder Joints](#)
- [Series A: Electrical Insulation of Al2O3-Coated Bonding Wire](#)
- [Production Testing Of Discrete Power Products](#)
- [Essential Inspection Requirements in the Era of Convergence](#)
- [Photosensitive Permanent Bonding Material Designed for Polymer/Metal Hybrid Bonding Applications](#)

### [Micro Inspection during Die Sort](#)

The AP+ offers 5-sided inspection down to 0.85um/pixel resolution to find the smallest defects on critical device surfaces including the top surface and all four die facet edges.

Royce Instruments



### [IC Device & Micro-Electronic Cleaning](#)

Answering the needs of packaging engineers, Kyzen offers modern cleaning chemistry proven effective for all IC devices & micro-electronics. Cost effective cleaning is no longer a challenge.

Kyzen Corporation



### [Dicing Die-Attach Film \(DDAF\) or Dicing Die-Attach Tape \(DDAT\)](#)

AI Technology pioneered the use of flexible die-attach film and paste adhesives for larger chip and die bonding. We now have extended our adhesive line. See more **A.I. Technology, Inc.**



Today's Sponsor



### Test Your Knowledge

What is an 'atoll'?

See answer below.

### [Better Bonds, with Atmospheric Plasma](#)

Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. [Click Here](#) to learn more.



Ontos Equipment Systems

### Press Releases

#### [Brewer Science unveils advanced packaging solutions at SEMICON Taiwan 2023](#)

Brewer Science, Inc., will present new developments in temporary and permanent bonding material technologies for advanced packaging this week at Asia's two premier ...

Brewer Science, Inc

#### [EV Group Hybrid Bonding and NIL Solutions Highlighted at SEMICON Taiwan](#)

EV Group (EVG) announced that new developments in 3D/heterogeneous integration and augmented reality (AR) waveguide manufacturing enabled by its advanced wafer ...

EV Group

#### [Vietnam Business Summit 2023: Paving the Way for Vietnam's Semiconductor Industry Growth](#)

Key semiconductor industry players and stakeholders including partners, government agencies, and academia will gather September 28-29 in Hanoi for the Vietnam Business ...

SEMI

### [SiC Vacuum Chucks for 3D Chip Stacks](#)

ISO|ITAR ARC makes:

- FC150, FC300, related tools
- Linear Ultrasonic 5-axis
- CNC machining.
- Porous Ceramic Wafer Chucks
- Grinding, Lapping, Dicing.

ARC



**Tech war: Huawei's silence over its latest Mate smartphone's advanced chip raises speculation on where and how it was made**

[SUMMARY](#)

Huawei's latest Mate smartphones have triggered speculation due to the company's tight-lipped stance on the advanced ...  
**South China Morning Post**

**Why Did Apple Endorse California's Right-to-Repair Bill?**

[SUMMARY](#)

California Adopts Sweeping Right-to-Repair Legislation: In a decisive move, California has passed comprehensive right-to-repair legislation, bolstering ...  
**IEEE Spectrum**

**Automotive Complexity, Supply Chain Strength Demands Tech Collaboration**

[SUMMARY](#)

The automotive industry faces soaring complexity as technological advancements surge, necessitating robust collaboration across the supply ...  
**Semiconductor Engineering**

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**Huawei unveils flagship smartphone with satellite connection support**

[SUMMARY](#)

Huawei accelerates efforts to bolster China-East Asia mobile connectivity by investing in cutting-edge mobile components for ...  
**Digitimes**

**Tech war: China exploring ways to make its own AI memory chips despite US sanctions**

[SUMMARY](#)

China defies US sanctions, embarks on developing indigenous AI memory chips. Undeterred by restrictions, China seeks ...  
**South China Morning Post**


**Worldwide Spending on Public Cloud Services is Forecast to Reach \$1.35 Trillion in 2027, According to New IDC Spending Guide**

[SUMMARY](#)

According to IDC's latest report, the global smartphone market shows robust growth despite ongoing challenges. Smartphone ...  
**IDC**

**Permanent Bonding Material**

In this paper, a novel negative-tone, photosensitive, polymeric bonding material is proposed that can be used as a dielectric enabling polymer/metal hybrid bonding.



**Brewer Science**

**Fusion and Hybrid Bonding Experts**

EVG's industry-leading process solutions, expertise and HI Competence Center accelerate the development and implementation of heterogeneous integration technology.



**EV Group**

**Quote of the Day**

"When I was young, I observed that nine out of 10 things I did were failures. So I did 10 times more work."

**George Bernard Shaw**

**Cost-saving coating platform**

Boost your throughput with ACS200 Gen3 TE. It allows for up to six spinner modules and enables inkjet printing for automated systems. Learn more.



**SUSS MicroTec**

**How to Cold Bump Pull?**

Learn how to perform an optimal Cold Bump Pull test on solder balls using tweezers. This guide covers test method settings and failures modes for CBP all types of bump testing.



**xyztec**

**What Year Was It?**

**Polish Government Signs Accord with Shipyard Workers**

Representatives of the communist government of Poland agree to the demands of striking shipyard workers in the city of Gdansk.



Former electrician Lech Walesa led the striking workers.  
**The day was Aug 31. What year was it?**

**Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages**

New fault isolation technique using 3D X-ray microscopy & LaserFIB to pinpoint, isolate & open a 20 µm wirebond without damage to adjacent wires.



**ZEISS Microscopy**

**SAWA SC-BM500E Automatic Stencil Cleaner**

Ultrasonic combined with spray cleaning provides an excellent solution for all kinds of applications including wafer bump and electroform stencils.



**Seika**

**Cartoon of the Day**



"If I figure out how many miles I've scrolled my computer mouse, can I write it off as business travel?"

Copyright © Randy Glasbergen

**"Prototype-to-Production" Pathway**

Future automation needs identified early in the development phase allows for the smooth transfer of development processes to a production environment. Download the Whitepaper.



**Finetech**

**Calendar**

■ **Sep 5, 2023: Advanced Packaging Summit 2023**

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Learn More

- [Sep 6, 2023: SEMICON Taiwan 2023](#)
- [Sep 6, 2023: Overview of semiconductor manufacturing for European Attendees](#)
- [Sep 7, 2023: EH&S Japan TC Chapter Meeting](#)

#### Permanent Bonding Material

In this paper, a novel negative-tone, photosensitive, polymeric bonding material is proposed that can be used as a dielectric enabling polymer/metal hybrid bonding.



**Brewer Science**

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**EV Group**

#### Test Your Knowledge Answer

What is an 'atoll'?

Answer: An atoll, sometimes called a coral atoll, is a ring-shaped coral reef including a coral rim that encircles a lagoon partially or completely. There may be coral islands or cays on the rim.

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#### **Circuitnet Media, LLC**

6 Liberty Square #2040, Boston MA 02109 USA

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